

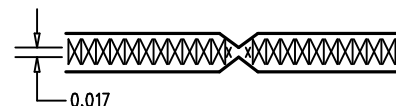
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.094	7	×	PLTD
0.055	30	□	PLTD
0.035	18	◇	PLTD
0.07	2	⊗	NPLTD
0.125	4	⊗	PLTD
0.015	116	A	PLTD

#### NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD  
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE  
ELECTRODEPOSITED TIN-LEAD COMPOSITION  
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 <b>LINEAR TECHNOLOGY</b> 1630 McCarthy Blvd Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN				
CHECK				
DESIGN	KIM T.	01-24-01		
ENGR	DEREK R.	01-24-01	TITLE: Fabrication Drawing	
			12 BIT / 5 MSPS ADC	
			SIZE A	DEMO DC362A-1*LTC1405CGN
				REV. A
SCALE = NONE			DES- 0000	
			SHT 1 of 1	